

METHODS FOR MANUFACTURING A ROLL CARRIER FOR ELECTRONIC
COMPONENTS, A CHIP-CARD MODULE AND A CHIP-CARD, AND A
CARRIER FOR ELECTRONIC COMPONENTS

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Abstract

The invention relates to a process for manufacturing a roll of flexible carrier (10, 20) bearing electronic components (14). This process comprises a step consisting in adding, to this flexible carrier (10, 20), electronic components (14),
10 themselves manufactured from a roll of flexible initial substrate. For example, the electronic components (14) may be manufactured on an initial substrate having a width allowing advantage to be taken of densification of the manufacture of the components (14) on this initial substrate. Subsequently, the singulated electronic components (14) are added to the flexible carrier (10, 20), allowing, for example,
15 packaging that is more suitable, than possible with the initial substrate, to a use of the electronic components (14), notably when the latter must be integrated into a chip-card (100). Thus, for example, the flexible carrier (10, 20) may be, or comprise, an adhesive (12, 23), which may or may not be conductive, and which is used to fasten, and optionally connect, each electronic component (14) to a
20 chip-card.

(Fig. 1)